PCN Number:	20151105000		PCN D	ate:	11/10/2015		
Title: Datasheet update for DAC3484							
Customer Contact:	PCN Manager Dept:		Quality Services				
Proposed 1 st Ship Date: 02/10/2016							
Change Type:							
Assembly Site	Design			Wafer Bump Site			
Assembly Process					Wafer Bump Material		
Assembly Materials					Wafer Bump Process		
		Test Site		Wafe			
Packing/Shipping/I	_abeling		ess		Wafer Fab Materials		
	DON Dataila		L	Wafer Fab Process			
PCN Details							
Description of Change: The product datasheet(s) is being updated as summarized below.							
The product datasneet(s) is being updated as summarized below.							
The following change history provides further details.							
-							
Texas Instruments							
DAC3484							
SLAS749E - MARCH 2011 - REVISED NOVEMBER 2015					www.ti.com		
Changes from Revision D (September 2015) to Revision E Page							
Changed I _(CLKVDD) Clock supply current Mode 1 max value from 95mA to 100mA							
The datasheet number will be changing.							
Device Family			Change From:		Change To:		
DAC3484			SLAS749D		SLAS749E		
These changes may be reviewed at the datasheet links provided.							
- ,							
http://www.ti.com/product/dac3484							
Reason for Change:							
To more accurately reflect device characteristics.							
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):							
Electrical specification performance changes as indicated above.							
Changes to product identification resulting from this PCN:							
None.							
Product Affected:							
DAC3484IRKD25	DAC3484IRKE	OT	DAC3484IZAY		DAC34	84IZAYR	
DAC3484IRKDR							
<u> </u>	•						

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com